DB22320 (Tentative)

Silicon epitaxial planar type

For rectification

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Package

- Code
  Mini2-F4-B
- Pin Name
  1: Cathode
  2: Anode

■ Marking Symbol: B5

■ Absolute Maximum Ratings $T_a = 25°C$

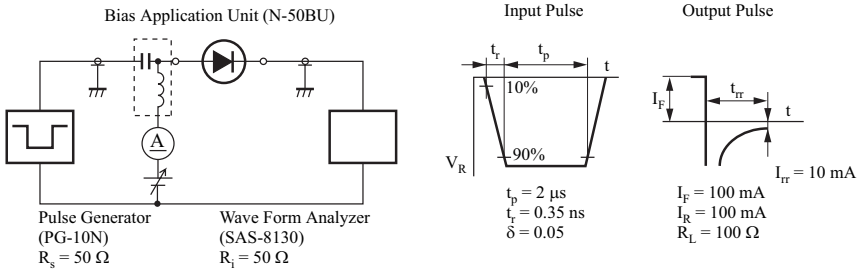
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V_{RRM}	30	V
Forward current (Average)	$I_{F(AV)}$	1.5	A
Non-repetitive peak forward surge current *	I_{FSM}	30	A
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	–55 to +125	°C

Note) *: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

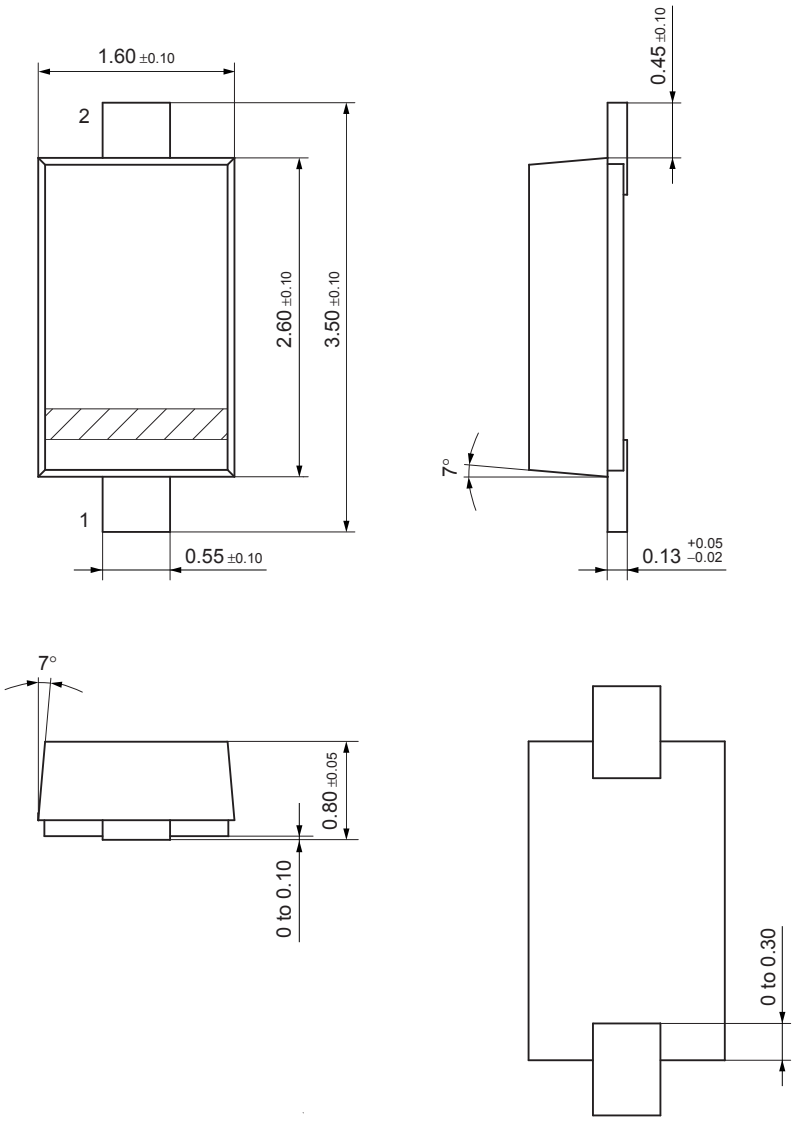
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 0.5$ A			0.38	V
	V_{F2}	$I_F = 1.0$ A			0.42	
Reverse current	I_R	$V_R = 30$ V			100	μA
Terminal capacitance	C_t	$V_R = 10$ V, f = 1 MHz		47		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100$ mA, $I_{rr} = 0.1 \times I_R$, $R_L = 100\ \Omega$		15		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. *: t_{rr} measurement circuit



Mini2-F4-B

Unit: mm



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